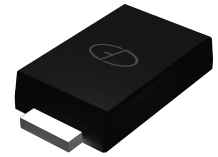


L2F6 thru L2F7

Surface Mount Glass Passivated Fast Recovery Rectifier
 Reverse Voltage 800 -1000V Forward Current 2A

Features

- Glass passivated fast recovery rectifiers
- Ideal for automated placement
- Low forward voltage drop
- Low leakage current
- Moisture sensitivity level:1 Per J-STD-020
- Solder dip 260°C, 10s
- Low profile



Package: eSGB (SMAF)



Maximum Ratings (T_A = 25°C unless otherwise noted)

Parameter	Symbol	L2F6	L2F7	Unit
Maximum Repetitive Peak Reverse Voltage	V _{RRM}	800	1000	V
Maximum RMS Voltage	V _{RMS}	560	700	V
Maximum DC Blocking Voltage	V _{DC}	800	1000	V
Maximum Average Forward Rectified Current	I _{F(AV)}	1.0		A
Peak Forward Surge Current (8.3 ms Single Half Sine-Wave Superimposed on Rated Load)	I _{FSM}	50		A
Operating Junction, Storage Temperature Range	T _J , T _{STG}	- 55 to + 150		°C

Electrical Characteristics (T_A = 25°C unless otherwise noted)

Parameter	Test Conditions	Symbol	L2F6	L2F7	Unit
Maximum Instantaneous Forward Voltage	I _F =2A, T _J =25°C	V _F	1.3		Volts
Maximum DC Reverse Current at Rated DC Blocking Voltage	T _A =25°C	I _R	5.0		μA
	T _A =125°C		50		
Typical Reverse Recovery Time	I _F =0.5A, I _R =1.0A, I _{rr} =0.25A	t _{rr}	500		nS
Typical Junction Capacitance	4.0 V, 1 MHz	C _J	11		pF
Typical Thermal Resistance	junction to mount	R _{θJM} ¹⁾	12		°C/W

Note1: Thermal resistance from junction to mount, mounted on PCB with 8.0×8.0mm copper pads

Ratings and Characteristics Curves

($T_A = 25^\circ\text{C}$ unless otherwise noted)

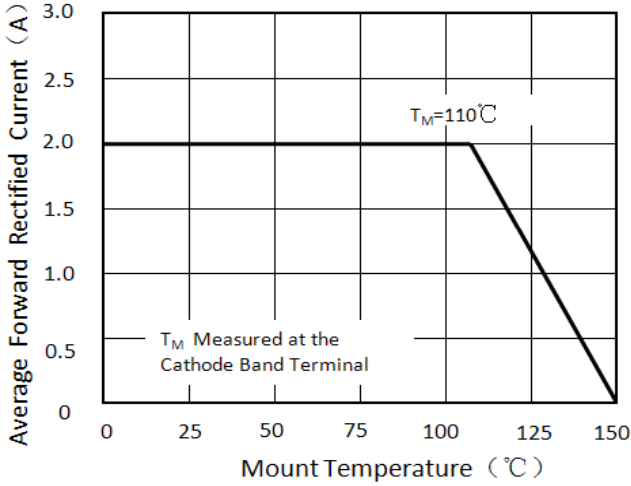


Figure 1. Forward Current Derating Curve

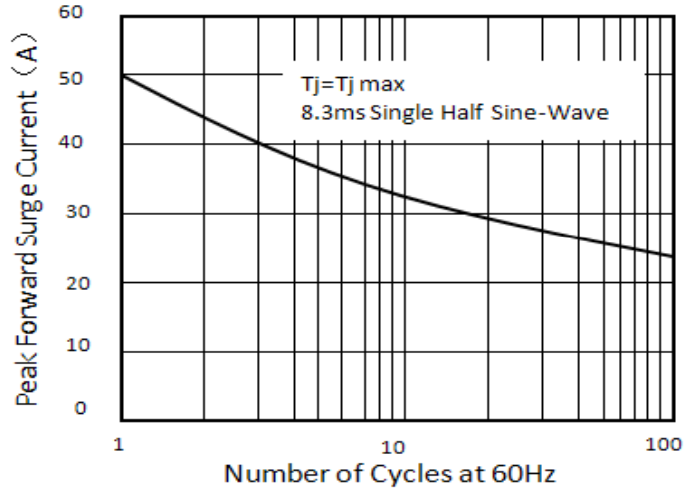


Figure 2. Maximum Non-Repetitive Peak Forward Surge Current

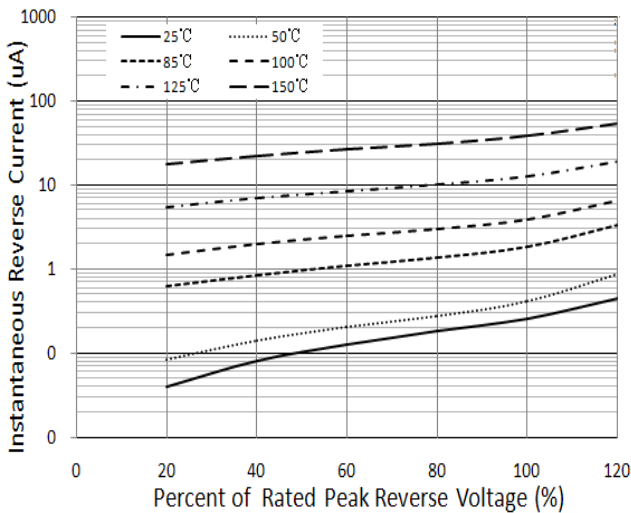


Figure 3. Typical Reverse Characteristics

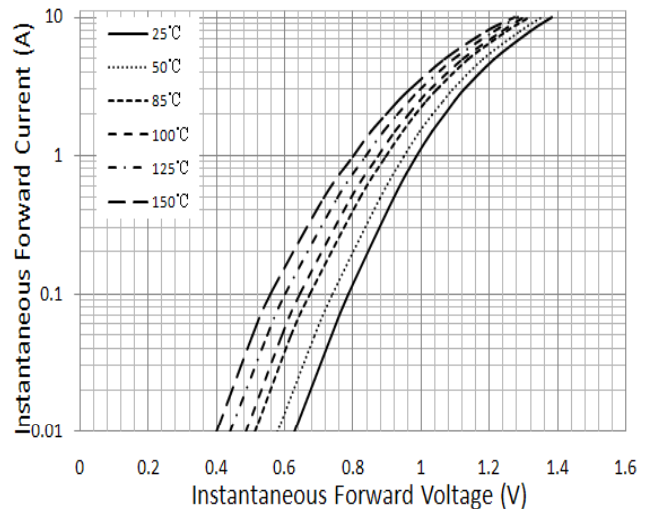


Figure 4. Typical Instantaneous Forward Characteristics

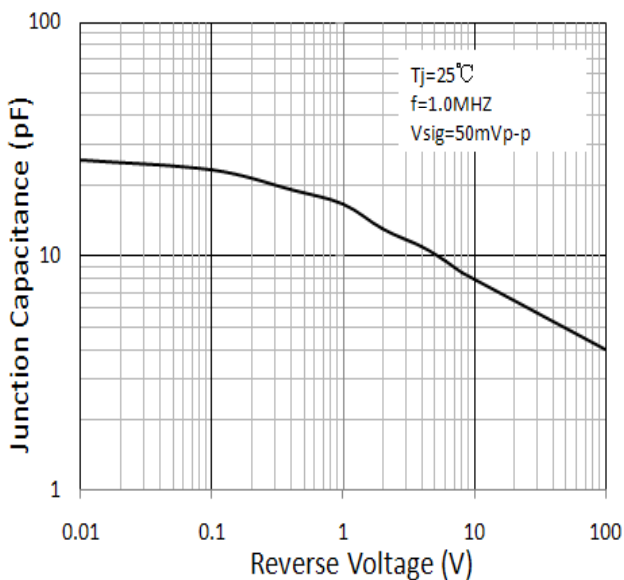


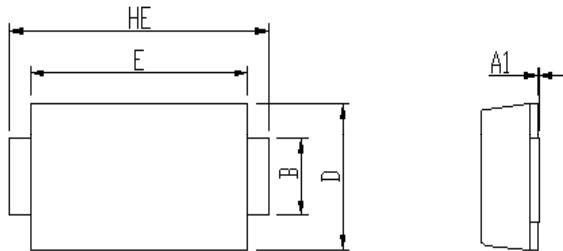
Figure 5. Typical Junction Capacitance

L2F6 thru L2F7

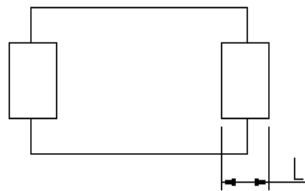
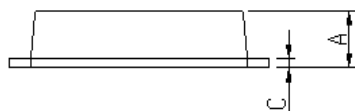
Surface Mount Glass Passivated Fast Recovery Rectifier
 Reverse Voltage 800-1000V Forward Current 2A

Package Outline Dimensions

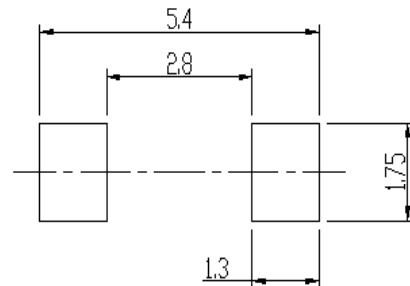
Package: eSGB (SMAF)



DIM	Unit: mm		Unit: inch	
	MIN	MAX	MIN	MAX
A	0.92	1.08	0.036	0.043
A1	0	0.1	0.000	0.004
B	1.25	1.45	0.049	0.057
C	0.1	0.25	0.004	0.010
D	2.6	2.8	0.102	0.110
E	4.1	4.3	0.161	0.169
L	0.7	1.1	0.028	0.043
HE	4.8	5.2	0.189	0.205



Soldering footprint



Packing Information

Packing quantities:

3000 pcs/Reel, 12mm Tape, 13" Reel

Tape & Reel Specification

